

OPEN-PIN-FIELD ARRAYS

SEARAY™ HIGH-SPEED/HIGH-DENSITY SYSTEMS

• .050" (1.27 mm) pitch grid for maximum grounding and routing flexibility

• Up to 560 single-ended I/Os or 140 differential pairs

 Rugged Edge Rate® contact system less prone to damage when "zippered" during unmating

• 7 to 40 mm stack heights

• Parallel, perpendicular, and coplanar applications

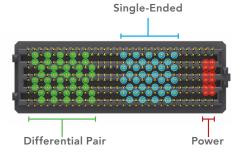
Solder on each tail for ease of processing;
 IPC-A-610F and IPC J-STD-001F Class 3
 solder joint

• High-speed cable assemblies for 50 Ω or 100 Ω solutions

• Press-fit tails available

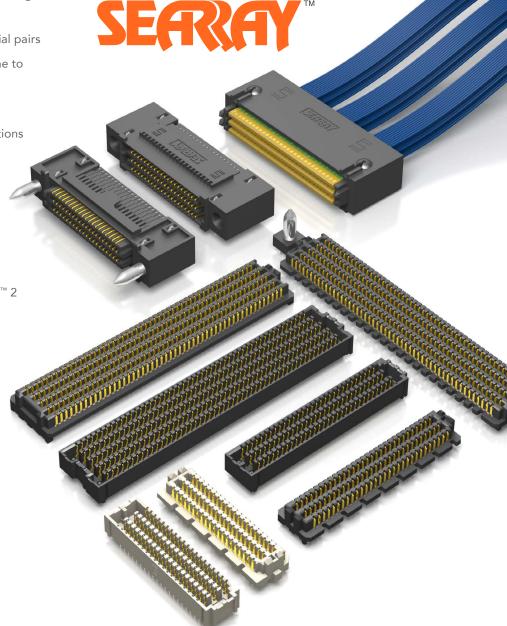
VITA 47, VITA 57.1, VITA 57.4, VITA 74, PISMO™ 2

Open-Pin-Field Flexibility









SEARAY™ PRODUCTS

- **SEAM** .050" Pitch Array Terminal
- SEAF .050" Pitch Array Socket
- SEAM-RA Right-angle, .050" Pitch Array Terminal
- SEAF-RA Right-angle, .050" Pitch Array Socket
- **SEAMP** Press-fit, .050" Pitch Array Terminal

- **SEAFP** Press-fit, .050" Pitch Array Socket
- **SEAFP-RA** Right-angle Press-fit, .050" Pitch Array Socket
- **SEAMI** 85 Ω Tuned, .050" Pitch Array Terminal
- SEAR Elevated Riser, .050" Pitch Array
- SEAC .050" Pitch Array Cable Assembly

SEARAY™ PRODUCT SOLUTIONS



SEAM

Open-Pin-Field Terminal 56 Gbps PAM4 performance; stack heights from 7 to 18.5 mm



SEAM-RA

Right-Angle Terminal 25 Gbps performance; guide post option



SEAF

Open-Pin-Field Socket 56 Gbps PAM4 performance; stack heights from 7 to 18.5 mm



SEAF-RA

Right-Angle Socket 25 Gbps performance; latching post option



SEAMP

Press-Fit Terminal 28 Gbps performance; guide post option



SEAFP

Press-Fit Socket Stack heights up to 16 mm



SEAFP-RA

Right-Angle Press-Fit Socket Guide post option



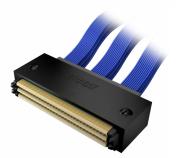
SEAMI

 $85\,\Omega$ Tuned Terminal 14 Gbps performance; stack heights up to 17.5 mm



SEAR

Elevated Riser
14 Gbps performance;
elevated stack heights
up to 40 mm



SEAC

High-Speed Cable Assembly 14 Gbps performance; 50Ω coax or 100Ω twinax cable with up to 240 I/Os



JSO

Precision Board Stacking Jack Screw Standoffs Assists unmating and reduces risk for component damage on boards